



Pentium®, 6x86, K6 Clock Synthesizer/Driver for Mobile PCs with Intel® 82430TX or Ali IV/V+ and 3 SO-DIMMs

Features

- Mixed 2.5V and 3.3V operation
- Complete clock solution for Pentium®, Cyrix, and AMD processor-based motherboards
 - Four CPU clocks at 2.5V or 3.3V with three dedicated CPU frequency select inputs
 - Six 3.3V SDRAM clocks, support three portable DIMMs
 - Seven synchronous PCI clocks, one free-running, one early
 - One 3.3V 48 MHz USB clock
 - One 3.3V 24 MHz IO clock
 - Two high drive 3.3V Ref. clocks at 14.318 MHz
- 1 ns–4 ns delay between CPU and PCI clocks
- I²C™ Serial Configuration Interface
- Factory-EPROM programmable output drive and slew rate for EMI customization
- Factory-EPROM programmable CPU clock frequencies for custom configurations
- Dedicated Power-down, CPU stop and PCI stop pins
- Available in space-saving 48-pin SSOP package

Functional Description

The CY2272 is a clock synthesizer/driver for a Pentium, Cyrix 6x86, or AMD K6 processor-based mobile PC using Intel®'s 82430TX, Aladdin IV+ or other similar chipsets.

The CY2272-1 outputs four CPU clocks at 2.5V or 3.3V. There are seven PCI clocks, running at one half the CPU clock frequency. One of the PCI clocks is free-running. Another leads

the PCI clocks by 1–4 ns. Additionally, the part outputs six 3.3V SDRAM clocks, one 3.3V USB clock at 48 MHz, one IO clock at 24 MHz, and two high-drive 3.3V reference clocks at 14.318 MHz.

The part possesses dedicated power-down, CPU stop, and PCI stop pins for power management control. When the CPU_STOP input is asserted, the CPU clock outputs are driven LOW. When the PCI_STOP input is asserted, the PCI clock outputs (except the free-running PCI clock) are driven LOW. When the PWR_DWN pin is asserted, the reference oscillator and PLLs are shut down, and all outputs are driven LOW.

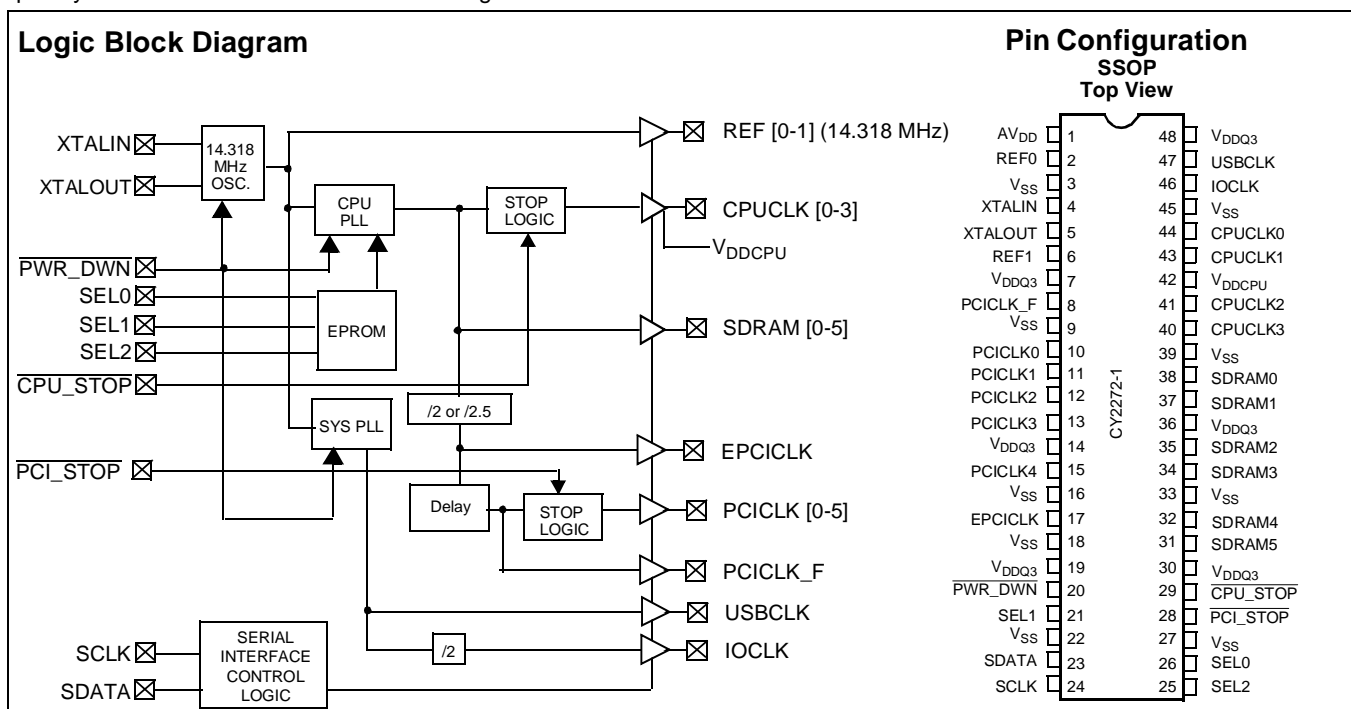
The CY2272 outputs are designed for low EMI emissions. Controlled rise and fall times, unique output driver circuits and factory-EPROM programmable output drive and slew-rate enable optimal configurations for EMI control.

CY2272 Selector Guide

Clock Outputs	-1
CPU (13.75, 15, 16.6, 18.75, 55, 60, 66.6, 75 MHz)	4
SDRAM	6
PCI (CPU/2MHz)	7 ^[1]
USB (48MHz)	1
IO (24MHz)	1
Ref (14.318MHz)	2
CPU-PCI delay	1–4 ns

Note:

1. One free-running PCI clock, one early PCI clock.



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Pin Summary

Name	Pins	Description
V _{DDQ3}	7, 14, 19, 30, 36, 48	3.3V Digital voltage supply
V _{DDCPU}	42	CPU Digital voltage supply, 2.5V or 3.3V
AV _{DD}	1	Analog voltage supply, 3.3V
V _{SS}	3, 9, 16, 18, 22, 27, 33, 39, 45	Ground
XTALIN ^[2]	4	Reference crystal input
XTALOUT ^[2]	5	Reference crystal feedback
PCI_STOP	28	Active LOW control input to stop PCI clocks (except free-running PCI clock)
CPU_STOP	29	Active LOW control input to stop CPU clocks
PWR_DWN	20	Active LOW control input to power down device
SDRAM[0–5]	38, 37, 35, 34, 32, 31	SDRAM clock outputs
SEL0	26	CPU frequency select input, bit 0 (See table below.)
SEL1	21	CPU frequency select input, bit 1 (See table below.)
SEL2	25	CPU frequency select input, bit 2 (See table below.)
CPUCLK[0:3]	44, 43, 41, 40	CPU clock outputs
PCICLK[0:4]	10, 11, 12, 13, 15	PCI clock outputs, at one-half the CPU frequency
PCICLK_F	8	Free-running PCI clock output
EPCICLK	17	Early PCI clock, leads PCI clocks by 1–4 ns
REF[0-1]	2, 6	3.3V Reference clock outputs, drive 45-pF loads
USBCLK	47	USB Clock output (48 MHz)
IOCLK	46	IO Clock output (24 MHz)
SDATA	23	Serial data input for serial configuration port
SCLK	24	Serial clock input for serial configuration port

Function Table, EPROM Programmable

I ² C Bit 4	SEL0	SEL1	SEL2	CPU/PCI Ratio	CPUCLK[0:3] SDRAM[0:5]	PCICLK[0:4] PCICLK_F EPCICLK	REF[0-1]	USBCLK	IOCLK
0	0	0	0	2	15 MHz	7.5 MHz	14.318 MHz	48 MHz	24 MHz
0	0	0	1	2	16.67 MHz	8.33 MHz	14.318 MHz	48 MHz	24 MHz
0	0	1	0	2.5	18.75 MHz	7.5 MHz	14.318 MHz	48 MHz	24 MHz
0	0	1	1	2	13.75 MHz	6.875 MHz	14.318 MHz	48 MHz	24 MHz
0	1	0	0	2	60.0 MHz	30.0 MHz	14.318 MHz	48 MHz	24 MHz
0	1	0	1	2	66.67 MHz	33.33 MHz	14.318 MHz	48 MHz	24 MHz
0	1	1	0	2.5	75.0 MHz	30.0 MHz	14.318 MHz	48 MHz	24 MHz
0	1	1	1	2	55.0 MHz	27.5 MHz	14.318 MHz	48 MHz	24 MHz

Note:

- For best accuracy, use a parallel-resonant crystal, C_{LOAD} = 18 pF.

Actual Clock Frequency Values

Clock Output	Target Frequency (MHz)	Actual Frequency (MHz)	PPM
CPUCLK	66.67	66.654	-195
CPUCLK	60.0	60.0	0
CPUCLK	75.0	75.0	0
USBCLK	48.0	48.008	167
IOCLK	24.0	24.004	167

CPU and PCI Clock Driver Strengths

- Matched impedances on both rising and falling edges on the output drivers
- Output impedance: 25Ω (typical) measured at 1.5V.

Power Management Logic

CPU_STOP	PCI_STOP	PWR_DWN	CPUCLK	PCICLK EPCICLK	PCICLK_F	Other Clocks	Osc.	PLLs
X	X	0	Low	Low	Stopped	Stopped	Off	Off
0	0	1	Low	Low	Running	Running	Running	Running
0	1	1	Low	CPU PLL / 2	Running	Running	Running	Running
1	0	1	As per Func. Tbl.	Low	Running	Running	Running	Running
1	1	1	As per Func. Tbl.	As per Func. Tbl.	Running	Running	Running	Running

Serial Configuration Map

- The Serial bits will be read by the clock driver in the following order:

Byte 0 - Bits 7, 6, 5, 4, 3, 2, 1, 0

Byte 1 - Bits 7, 6, 5, 4, 3, 2, 1, 0

.

Byte N - Bits 7, 6, 5, 4, 3, 2, 1, 0

- Reserved and unused bits should be programmed to "0".
- I²C Address for the CY2273 is:

A6	A5	A4	A3	A2	A1	A0	R/W
1	1	0	1	0	0	1	----

Byte 0: Functional and Frequency Select Clock Register (1 = Enable, 0 = Disable)

Bit	Pin #	Description	
Bit 7	--	(Reserved) drive to '0'	
Bit 6	--	(Reserved) drive to '0'	
Bit 5	--	(Reserved) drive to '0'	
Bit 4	--	Frequency Select (Refer to Freq. Sel. Table)	
Bit 3	--	(Reserved) drive to '0'	
Bit 2	--	(Reserved) drive to '0'	
Bit 1 Bit 0	--	Bit 1 1 1 0 0	Bit 0 1 - Three-State 0 - N/A 1 - Testmode 0 - Normal Operation

Select Functions based on Byte 0

Functional Description	Outputs					
	CPU	PCI, PCI_F	SDRAM	Ref	USBCLK	IOCLK
Three-State	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z
Test Mode ^[4]	TCLK/2 ^[3]	TCLK/4	TCLK/2	TCLK	TCLK/2	TCLK/4

Notes:

3. TCLK supplied on the XTALIN pin in Test Mode.
4. Valid only for SEL2=1, SEL1=0, SEL0=1.

**Byte 1: CPU Active/Inactive Register
(1 = Active, 0 = Inactive), Default = Active**

Bit	Pin #	Description
Bit 7	47	USBCLK (Active/Inactive)
Bit 6	46	IOCLK (Active/Inactive)
Bit 5	N/A	(Reserved) drive to '0'
Bit 4	N/A	Not used - drive to '0'
Bit 3	40	CPUCLK3 (Active/Inactive)
Bit 2	41	CPUCLK2 (Active/Inactive)
Bit 1	43	CPUCLK1 (Active/Inactive)
Bit 0	44	CPUCLK0 (Active/Inactive)

**Byte 2: PCI Active/Inactive Register
(1 = Active, 0 = Inactive), Default = Active**

Bit	Pin #	Description
Bit 7	--	(Reserved) drive to '0'
Bit 6	7	PCICLK_F (Active/Inactive)
Bit 5	15	EPCICLK (Active/Inactive)
Bit 4	14	PCICLK4 (Active/Inactive)
Bit 3	12	PCICLK3 (Active/Inactive)
Bit 2	11	PCICLK2 (Active/Inactive)
Bit 1	10	PCICLK1 (Active/Inactive)
Bit 0	8	PCICLK0 (Active/Inactive)

**Byte 3: SDRAM Active/Inactive Register
(1 = Active, 0 = Inactive), Default = Active**

Bit	Pin #	Description
Bit 7	28	(Reserved) drive to '0'
Bit 6	29	(Reserved) drive to '0'
Bit 5	31	SDRAM5 (Active/Inactive)
Bit 4	32	SDRAM4 (Active/Inactive)
Bit 3	34	SDRAM3 (Active/Inactive)
Bit 2	35	SDRAM2 (Active/Inactive)
Bit 1	37	SDRAM1 (Active/Inactive)
Bit 0	38	SDRAM0 (Active/Inactive)

**Byte 4: SDRAM Active/Inactive Register
(1 = Active, 0 = Inactive), Default = Active**

Bit	Pin #	Description
Bit 7	N/A	Not used - drive to '0'
Bit 6	N/A	Not used - drive to '0'
Bit 5	N/A	Not used - drive to '0'
Bit 4	N/A	Not used - drive to '0'
Bit 3	17	Not used - drive to '0'
Bit 2	18	Not used - drive to '0'
Bit 1	20	Not used - drive to '0'
Bit 0	21	Not used - drive to '0'

**Byte 5: Peripheral Active/Inactive Register
(1 = Active, 0 = Inactive), Default = Active**

Bit	Pin #	Description
Bit 7	N/A	(Reserved) drive to '0'
Bit 6	N/A	(Reserved) drive to '0'
Bit 5	N/A	(Reserved) drive to '0'
Bit 4	N/A	(Reserved) drive to '0'
Bit 3	N/A	(Reserved) drive to '0'
Bit 2	N/A	(Reserved) drive to '0'
Bit 1	6	REF1 (Active/Inactive)
Bit 0	2	REF0 (Active/Inactive)

Byte 6: Reserved, for future use

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Supply Voltage -0.5 to +7.0V
 Input Voltage -0.5V to $V_{DD}+0.5$

Storage Temperature (Non-Condensing) ... -65°C to +150°C
 Max. Soldering Temperature (10 sec) +260°C
 Junction Temperature +150°C
 Package Power Dissipation 1W
 Static Discharge Voltage >2000V
 (per MIL-STD-883, Method 3015, like V_{DD} pins tied together)

Operating Conditions^[5]

Parameter	Description	Min.	Max.	Unit
AV_{DD} , V_{DDQ3}	Analog and Digital Supply Voltage	3.135	3.465	V
V_{DDCPU}	CPU Supply Voltage	2.375 3.135	2.9 3.465	V
T_A	Operating Temperature, Ambient	0	70	°C
C_L	Max. Capacitive Load on CPUCLK, USBCLK, IOCLK EPCICK, PCICK SDRAM REF [0,1]	10 30 20 20	20 30 30 45	pF
$f_{(REF)}$	Reference Frequency, Oscillator Nominal Value	14.318	14.318	MHz

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions		Min.	Max.	Unit
V_{IH}	High-level Input Voltage	Except Crystal Inputs		2.0		V
V_{IL}	Low-level Input Voltage	Except Crystal Inputs			0.8	V
V_{ILiic}	Low-level Input Voltage	I^2C inputs only			0.7	V
V_{OH}	High-level Output Voltage	$V_{DDCPU} = V_{DDQ2} = 2.375V$	$I_{OH} = 16\text{ mA}$ CPUCLK	2.0		V
V_{OL}	Low-level Output Voltage	$V_{DDCPU} = V_{DDQ2} = 2.375V$	$I_{OL} = 27\text{ mA}$ CPUCLK		0.4	V
V_{OH}	High-level Output Voltage	V_{DDQ3} , AV_{DD} , $V_{DDCPU} = 3.135V$	$I_{OH} = 16\text{ mA}$ CPUCLK	2.4		V
			$I_{OH} = 36\text{ mA}$ SDRAM			
			$I_{OH} = 32\text{ mA}$ PCICK			
			$I_{OH} = 26\text{ mA}$ USBCLK IOCLK			
			$I_{OH} = 36\text{ mA}$ REF[0-1]			
V_{OL}	Low-level Output Voltage	V_{DDQ3} , AV_{DD} , $V_{DDCPU} = 3.135V$	$I_{OL} = 27\text{ mA}$ CPUCLK		0.4	V
			$I_{OL} = 29\text{ mA}$ SDRAM			
			$I_{OL} = 26\text{ mA}$ PCICK			
			$I_{OL} = 21\text{ mA}$ USBCLK IOCLK			
			$I_{OL} = 29\text{ mA}$ REF[0-1]			
I_{IH}	Input High Current	$V_{IH} = V_{DD}$		-10	+10	μA
I_{IL}	Input Low Current	$V_{IL} = 0V$			10	μA
I_{OZ}	Output Leakage Current	Three-state		-10	+10	μA
I_{DD}	Power Supply Current	$V_{DD} = 3.465V$, $V_{IN} = 0$ or V_{DD} , Loaded Outputs, CPU clocks = 66.67 MHz			300	mA
I_{DD}	Power Supply Current	$V_{DD} = 3.465V$, $V_{IN} = 0$ or V_{DD} , Unloaded Outputs			140	mA
I_{DDS}	Power-down Current	Current draw in power-down state			150	μA

Note:

5. Electrical parameters are guaranteed with these operating conditions.

Switching Characteristics^[6]

Parameter	Output	Description	Test Conditions	Min.	Typ.	Max.	Unit
t ₁	All	Output Duty Cycle ^[7]	$t_1 = t_{1A} \div t_{1B}$	45	50	55	%
t ₂	CPUCLK	CPU Clock Rising and Falling Edge Rate	Between 0.4V and 2.0V, V _{DDCPU} = 2.5V Between 0.4V and 2.4V, V _{DDCPU} = 3.3V	0.75		4.0	V/ns
t ₂	REF[0-1]	REF Clock Rising and Falling Edge Rate	Between 0.4V and 2.4V	0.75		4.0	V/ns
t ₂	PCICLK, EPCICLK	PCI, EPCI, Clock Rising and Falling Edge Rate	Between 0.4V and 2.4V	0.9		4.0	V/ns
t ₂	SDRAM	SDRAM Rising and Falling Edge Rate	Between 0.4V and 2.4V	0.9		4.0	V/ns
t ₃	CPUCLK	CPU Clock Rise Time	Between 0.4V and 2.0V, V _{DDCPU} = 2.5V Between 0.4V and 2.4V, V _{DDCPU} = 3.3V	0.4 0.5		2.13 2.67	ns
t ₄	CPUCLK	CPU Clock Fall Time	Between 2.0V and 0.4V, V _{DDCPU} = 2.5V Between 2.4V and 0.4V, V _{DDCPU} = 3.3V	0.4 0.5		2.13 2.67	ns
t ₅	CPUCLK	CPU-CPU Clock Skew	Measured at 1.25V, V _{DDCPU} = 2.5V Measured at 1.5V, V _{DDCPU} = 3.3V		100	250	ps
t ₆	CPUCLK, PCICLK	CPU-PCI Clock Skew	Measured at 1.25V for 2.5V clocks, and at 1.5V for 3.3V clocks	1.0	2.0	4.0	ns
t ₇	CPUCLK, SDRAM	CPU-SDRAM Clock Skew	Measured at 1.25V for 2.5V clocks, and at 1.5V for 3.3V clocks - Measured at 66.66 MHz - Measured at 75 MHz.			650 750	ps ps
t ₈	PCICLK, PCICLK	PCI-PCI Clock Skew PCI-PCI_F Clock Skew	Measured at 1.5V Measured at 1.5V			250 350	ps ps
t ₉	EPCICLK, PCICLK	EPCI-PCI Clock Skew	Measured at 1.5V for 3.3V clocks	1.0	2.0	4.0	ns
t ₁₀	CPUCLK ^[7]	Cycle-Cycle Clock Jitter				400	ps
t ₁₀	SDRAM ^[7]	Cycle-Cycle Clock Jitter				300	ps
t ₁₁	PCICLK, EPCICLK ^[7]	Cycle-Cycle Clock Jitter				400	ps
t ₁₂	CPUCLK, PCICLK, EPCI, SDRAM	Power-up Time	CPU, PCI, EPCI, and SDRAM clock stabilization from power-up			3	ms
t ₁₃	CPUCLK, PCICLK, SDRAM	/4 Frequency Slew Time	Time for CPU, EPCI, PCI, and SDRAM clock frequency to change from F to F/4 after select input change		10	25	cycles

Notes:

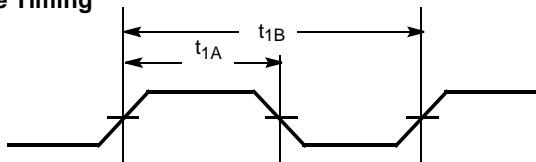
6. All parameters specified with maximum loaded outputs, measured with select lines = 101 and 110 (sel0, sel1, sel2).
7. Measured at 1.5V for 3.3V clocks and at 1.25V for 2.5V clocks.

Timing Requirement for the I²C Bus

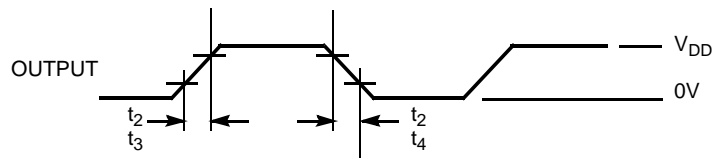
Parameter	Description	Min.	Max.	Unit
t ₁₂	SCLK Clock Frequency	0	100	kHz
t ₁₃	Time the bus must be free before a new transmission can start	4.7		μs
t ₁₄	Hold time start condition. After this period the first clock pulse is generated.	4		μs
t ₁₅	The LOW period of the clock.	4.7		μs
t ₁₆	The HIGH period of the clock.	4		μs
t ₁₇	Set-up time for start condition. (Only relevant for a repeated start condition.)	4.7		μs
t ₁₈	Hold time DATA for CBUS compatible masters. for I ² C devices	5 0		μs
t ₁₉	DATA input set-up time	250		ns
t ₂₀	Rise time of both SDATA and SCLK inputs		1	μs
t ₂₁	Fall time of both SDATA and SCLK inputs		300	ns
t ₂₂	Set-up time for stop condition	4.0		μs

Switching Waveforms

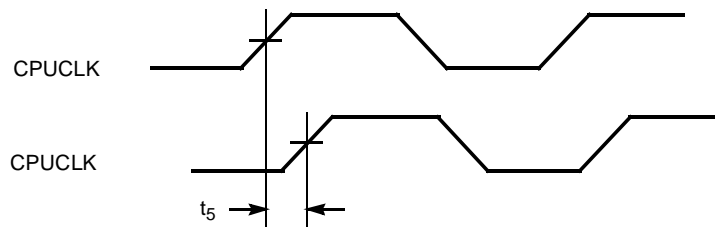
Duty Cycle Timing

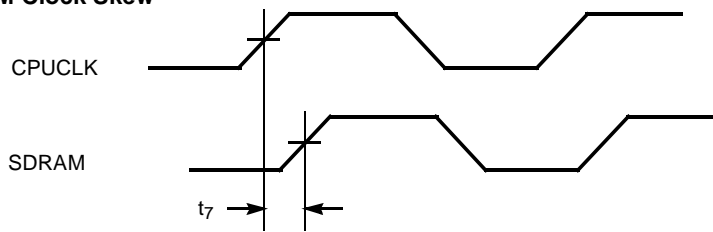
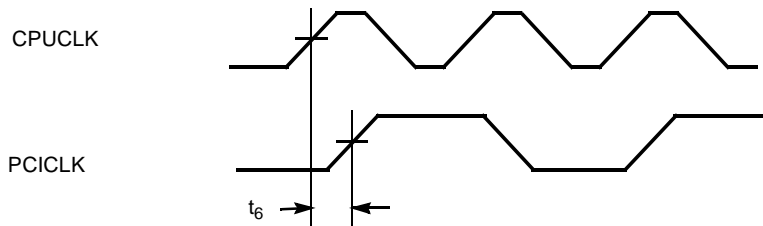
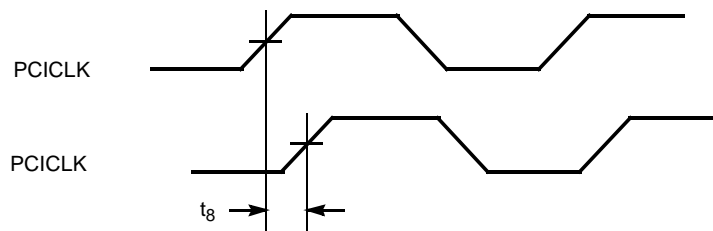
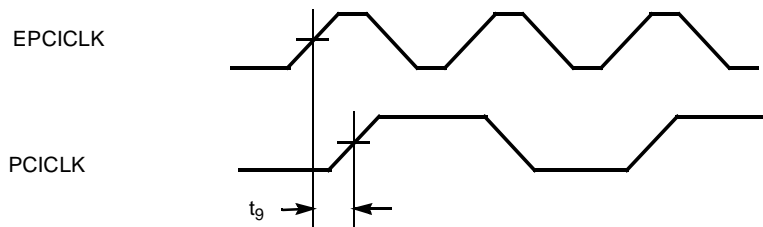
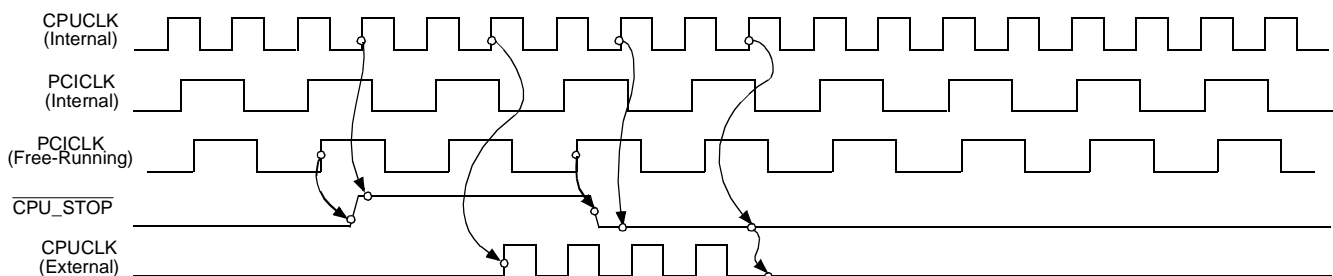


All Outputs Rise/Fall Time

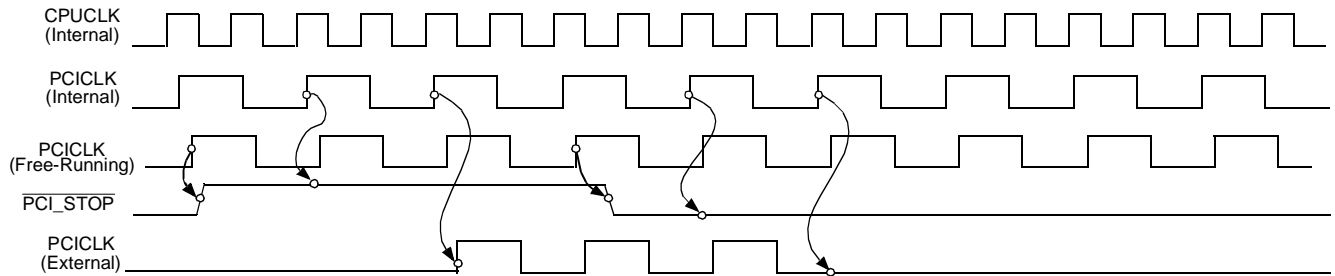
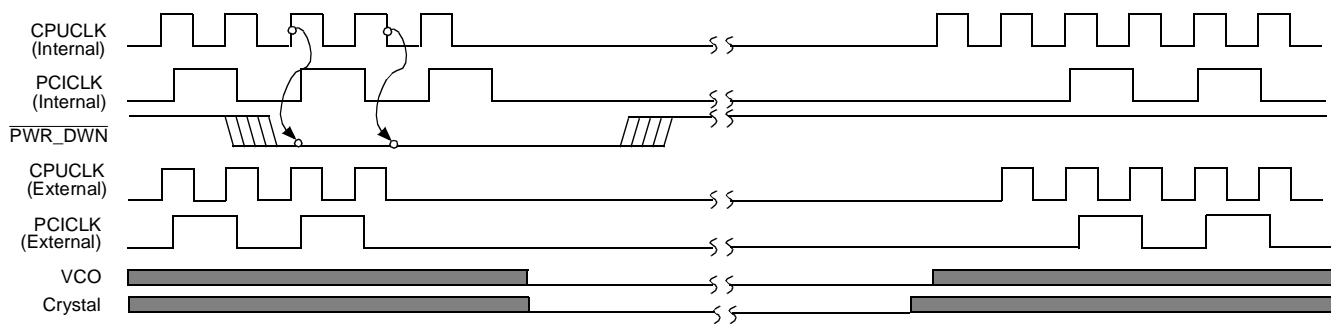


CPU-CPU Clock Skew

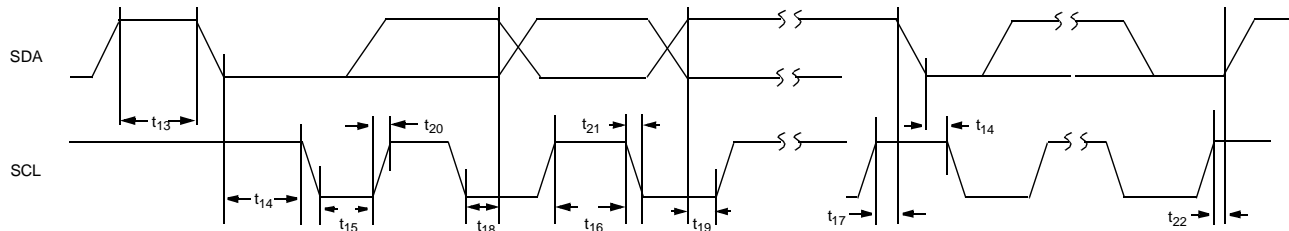


Switching Waveforms (continued)
CPU-SDRAM Clock Skew

CPU-PCI Clock Skew

PCI-PCI Clock Skew

EPCI-PCI Clock Skew

CPU_STOP^[8, 9]

Notes:

8. CPUCLK on and CPUCLK off latency is 2 or 3 CPUCLK cycles.
9. CPU_STOP may be applied asynchronously. It is synchronized internally.

Switching Waveforms (continued)
PCI_STOP^[10, 11]

PWR_DOWN


Shaded section on the VCO and Crystal waveforms indicates that the VCO and crystal oscillator are active, and there is a valid clock.

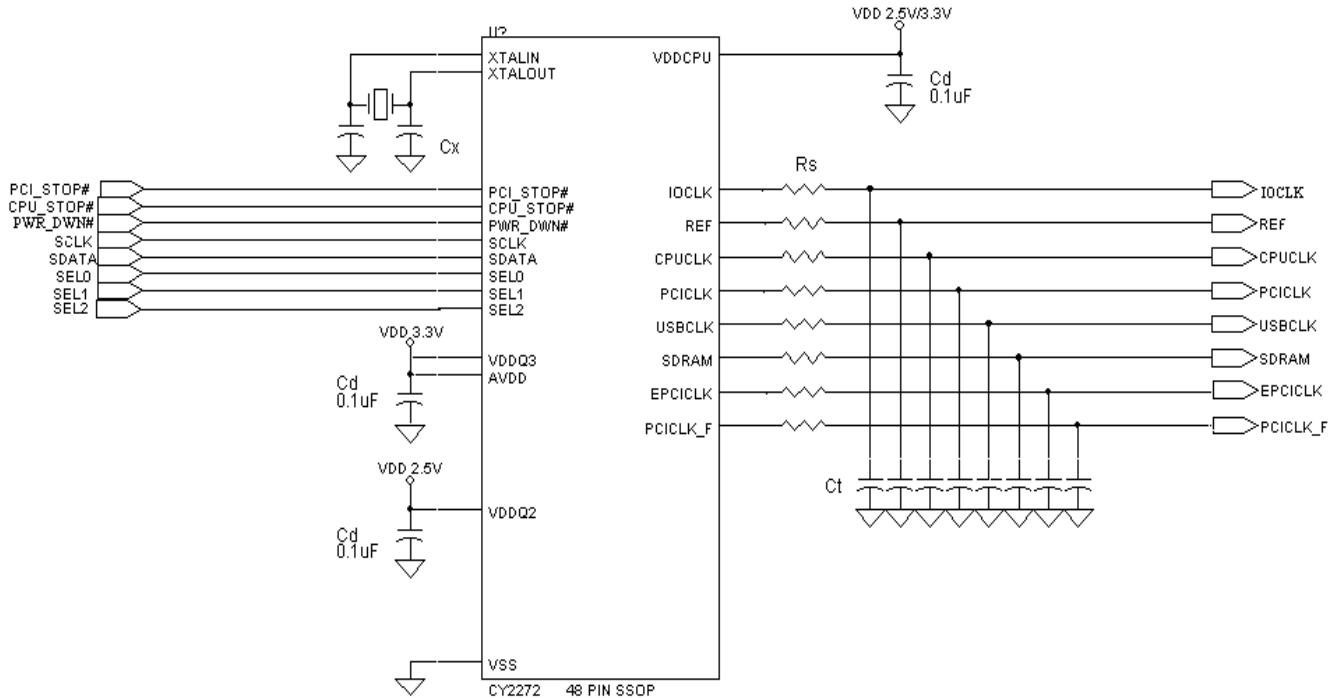
Timing Requirements for the I²C Bus

Notes:

10. PCICLK on and PCICLK off latency is 1 rising edge of the external PCICLK.
11. PCI_STOP may be applied asynchronously. It is synchronized internally.

Application Information

Clock traces must be terminated with either series or parallel termination, as they are normally done.

Application Circuit



Cd = DECOUPLING CAPACITORS

Ct = OPTIONAL EMI-REDUCING CAPACITORS

Cx = OPTIONAL LOAD MATCHING CAPACITOR

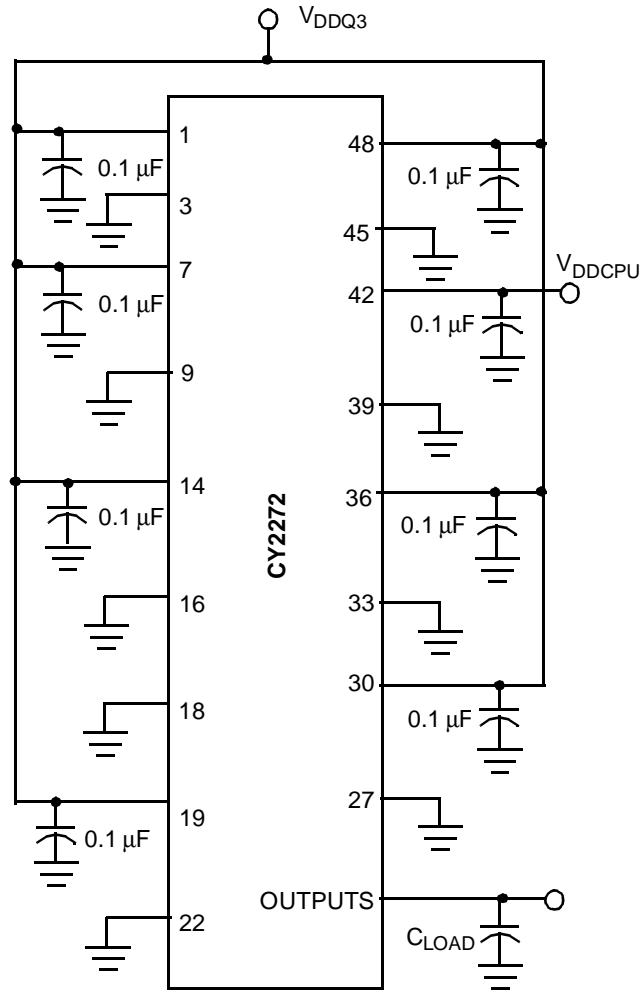
Rs = SERIES TERMINATING RESISTORS

Summary

- A parallel-resonant crystal should be used as the reference to the clock generator. The operating frequency and C_{LOAD} of this crystal should be as specified in the data sheet. Optional trimming capacitors may be needed if a crystal with a different C_{LOAD} is used. Footprints must be laid out for flexibility.
- Surface mount, low-ESR, ceramic capacitors should be used for filtering. Typically, these capacitors have a value of 0.1 μ F. In some cases, smaller value capacitors may be required.
- The value of the series terminating resistor satisfies the following equation, where R_{trace} is the loaded characteristic impedance of the trace, R_{out} is the output impedance of the clock generator (specified in the data sheet), and R_{series} is the series terminating resistor.

$$R_{series} \geq R_{trace} - R_{out}$$

- Footprints must be laid out for optional EMI-reducing capacitors, which should be placed as close to the terminating resistor as is physically possible. Typical values of these capacitors range from 4.7 pF to 22 pF.
- A Ferrite Bead **may** be used to isolate the Board V_{DD} from the clock generator V_{DD} island. Ensure that the Ferrite Bead offers greater than 50 Ω impedance at the clock frequency, under loaded DC conditions. Please refer to the application note "Layout and Termination Techniques for Cypress Clock Generators" for more details.
- If a Ferrite Bead is used, a 10 μ F–22 μ F tantalum bypass capacitor should be placed close to the Ferrite Bead. This capacitor prevents power supply droop during current surges.

Test Circuit


Note: All Capacitors must be placed as close to the pins as is possible

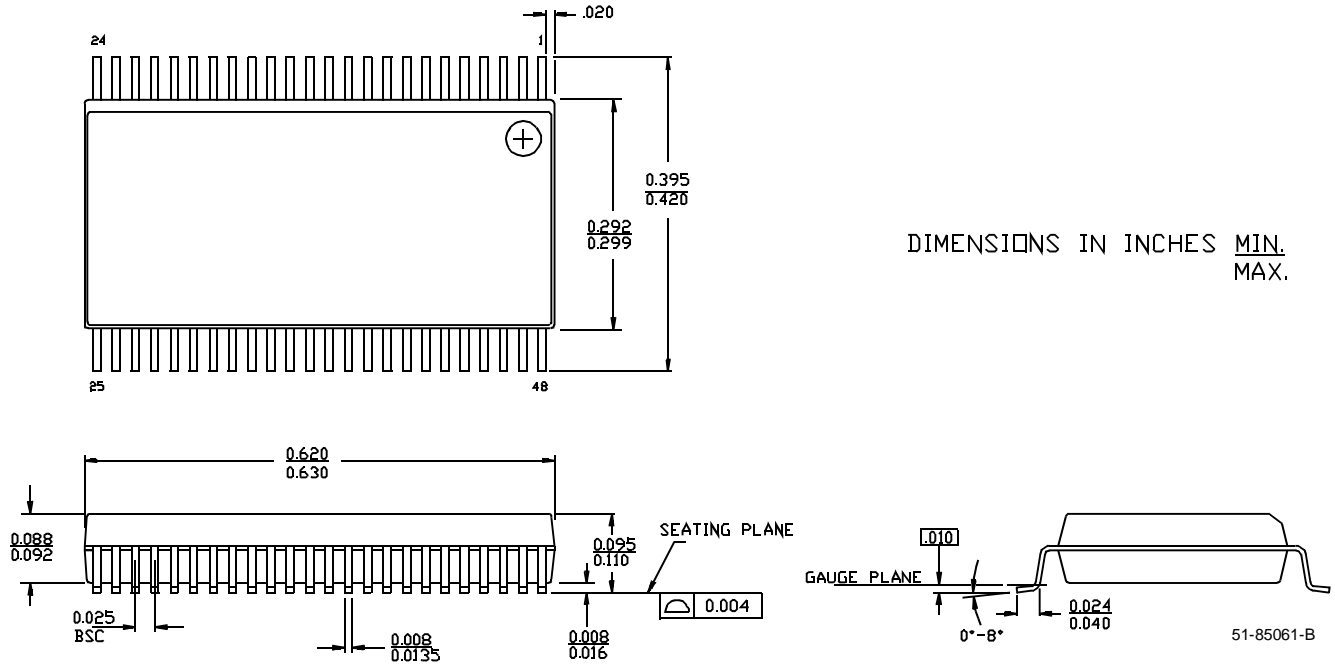
Ordering Information

Ordering Code	Package Name	Package Type	Operating Range
CY2272PVC-1	O48	48-Pin SSOP	Commercial

Document #: 38-00607-C

Package Diagram

48-Lead Shrink Small Outline Package O48



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